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**PRINTED CIRCUIT BOARDS FOR ELECTRONIC DEVICE  
PACKAGES HAVING GLASS FREE NON-CONDUCTIVE  
LAYERS AND METHOD OF FORMING SAME**

**ABSTRACT**

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A printed circuit board for use in an electronic device package such as a ball grid array package or organic chip carrier package includes a glass-free dielectric for separating and insulating power cores, circuitry or plated through holes from each other to prevent shorts caused by a migration of conductive material along glass-based prepreg substrates.

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